2024/

ADEKA REMYLOP CLS-1132

Product Features

- One-component heat curing adhesive
- Rapid curing type
- Low curing shrinkage
- Epoxy type（Halogen-free available）
- NIR laser curable

Properties（uncured）

Viscosity / 25℃	2^{-1}	76	Pa・s
	20^{-1}	28	Pa・s
Thixotropic value	$2^{-1}/20^{-1}$	2.7	
Specific gravity		1.57	
Filler content		55	wt %
Nonvolatile content		＞99	%
Pot Life	25 ℃	＞24	hrs
Shelf Life	≦－20 ℃	＞180	days

Cured Material Properties

Glass transition temperature	TMA	101	℃
	DMA	121	℃
Hardness	ShoreD	＞D80	
Storage modulus/ 25℃	DMA	5.9	GPa
Coefficient of linear expansion	α1	26	ppm
Thermal conductivity	Transient hot wire method	0.28	W/m・K
Curing shrinkage	Densitometry method	2.2	%

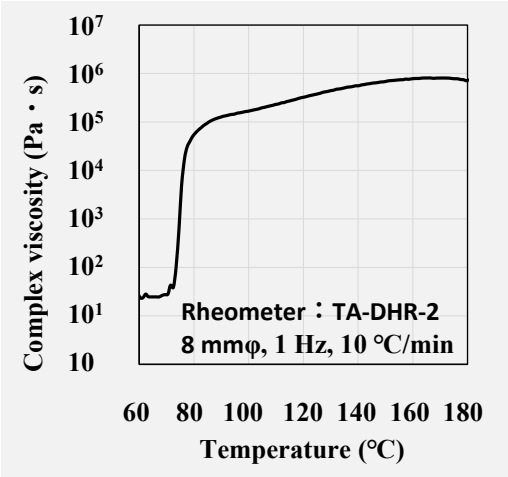
DSC：SII DCS6220 25 – 250 ℃ (10 ℃/min)
DMA：TA RSA-G2 -50 – 250 ℃ (10 ℃/min), curing condition；125 ℃×1 hr
TMA：SII TMA/SS6100 -55 – 150 ℃ (5 ℃/min), curing condition；125 ℃×1 hr
Thermal conductivity：C-Therm Tci, curing condition；125 ℃×1 hr

Recommended Curing Conditions

125	℃	1.0	hr

Lase curing condition (e.g.)：940 nm, 4 mmφ, 3 W, 3 sec.

Curing behavior



Usage

【Storage】 Store frozen (below -20 ℃)

【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.
Recommended defrosting time : Syringe ;. 25 ℃, 1 h or more.
Barrel ; 25 ℃, 2 h or more.

【Curing】 When curing more than 1 g, please be careful of runaway reactions.

【Disposal】 Please refer to SDS for proper treatment.

【Others】 Please contact us at the following

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